

DETAIL B
SCALE 8 : 1

- NOTES:
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE 0.50 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al₂O₃ BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.
 8. TWO VCC PADS ELECTRICALLY CONNECTED TO PIN 24 (PAGE 2)

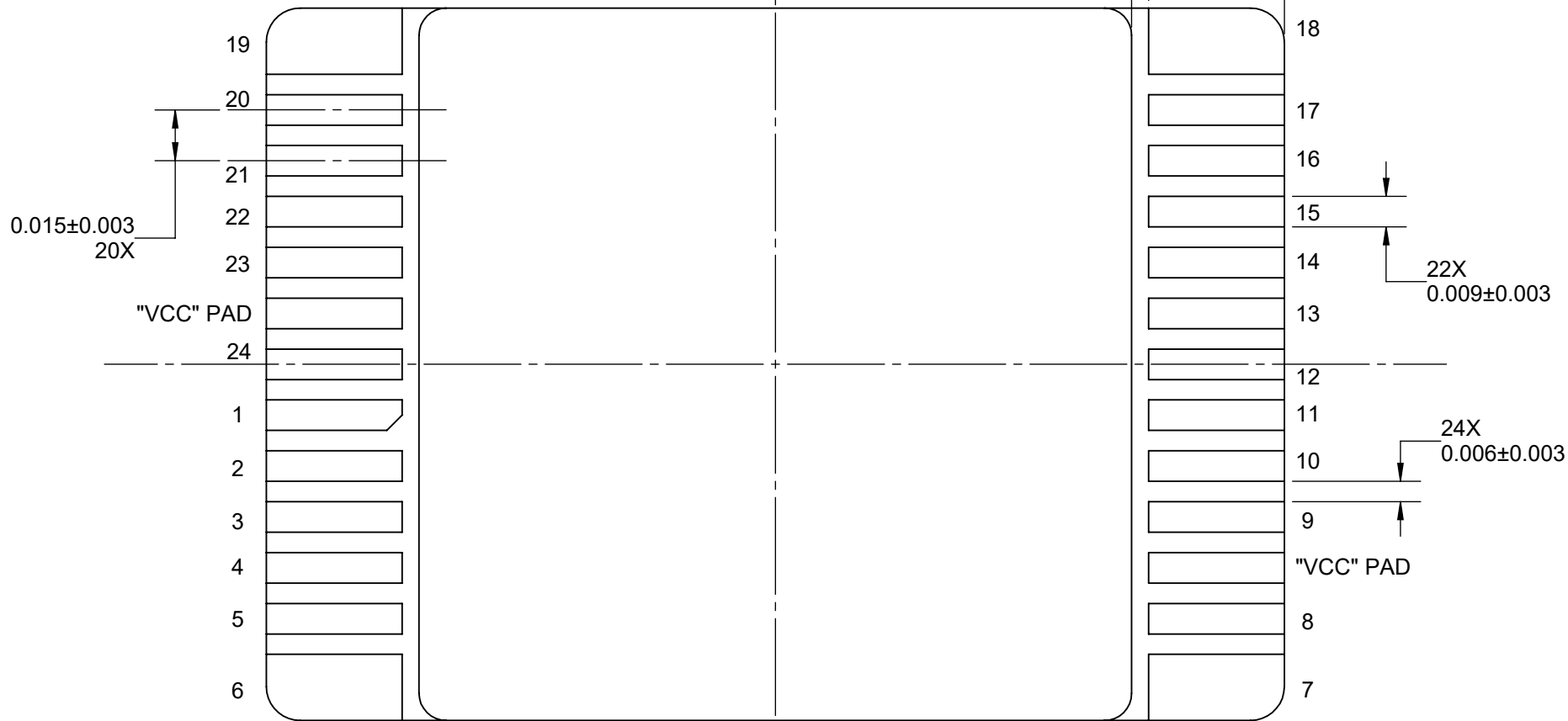
PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP24F3-SB-N210	GOLD	168012

APPROVALS	DATE	TopLine®			
DRAWN T. Au	1/22/2020				
ENG M. Hart	1/22/2020	TITLE CERDIP24F3-SB-N210 PAD 210 x 210 MIL			
MFG		SCALE 4:1	SIZE A	DRAWING NO. 168012	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

BONDING PADS

0.005 NOM
PULL BACK
NO RUNDOWN

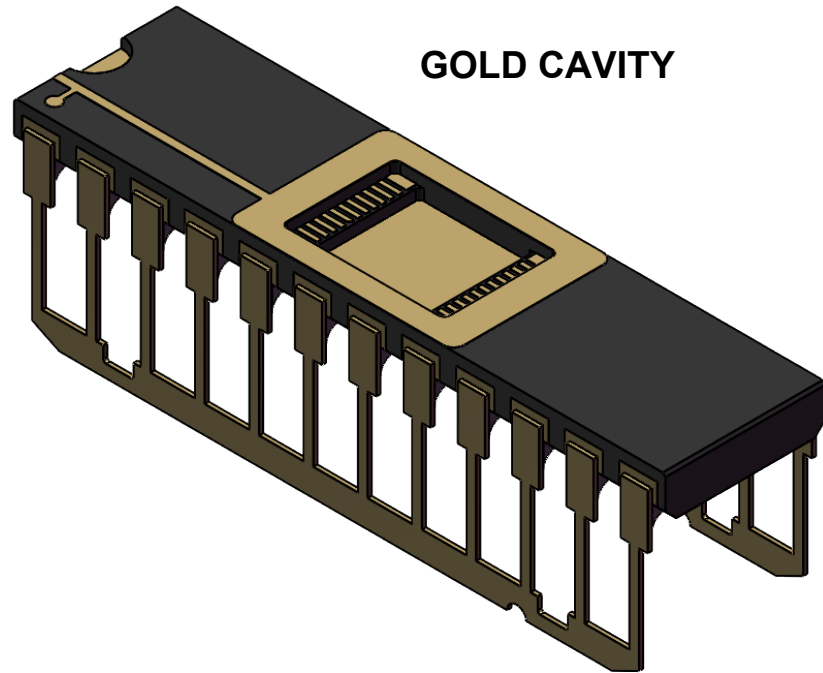
0.032 MIN
PAD LENGTH



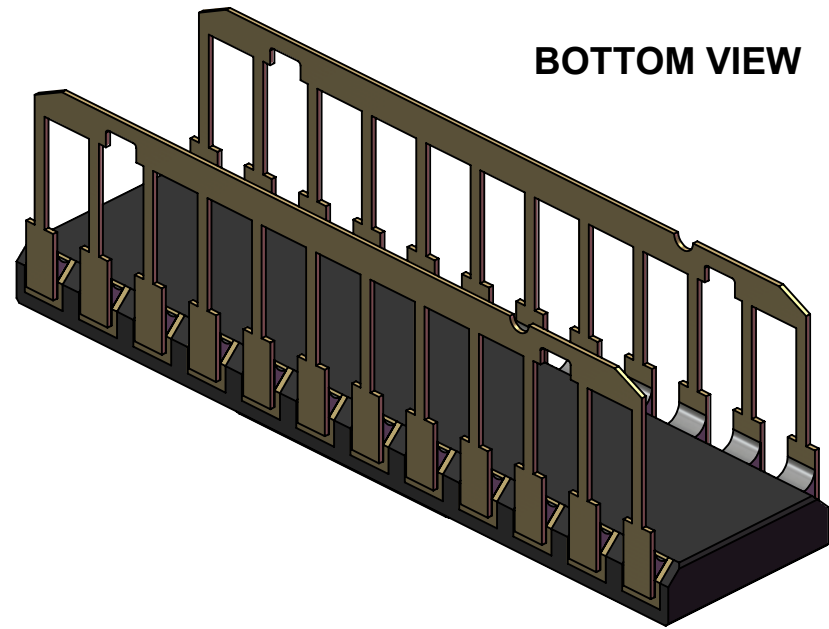
NOTE: TWO "VCC" PADS ELECTRICALLY CONNECTED TO PIN 24

TopLine®			
TITLE CERDIP24F3-SB-N210 PAD 210 x 210 MIL			
SCALE 8:1	SIZE A	DRAWING NO. 168012	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

BONDING PADS



GOLD CAVITY



BOTTOM VIEW

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP24F3-SB-N210	GOLD	168012

TopLine®			
TITLE		CERDIP24F3-SB-N210 PAD 210 x 210 MIL	
SCALE	SIZE	DRAWING NO.	REV
8:1	A	168012	A
DO NOT SCALE DRAWING			SHEET 3 OF 3